

SINGLE PHASE GLASS PASSIVATED BRIDGE RECTIFIERS

Features

- ◆ Glass Passivated Chip Junction
- ◆ Reverse Voltage - 200 to 1000 V
- ◆ Forward Current - 1 A
- ◆ High surge current capability
- ◆ Designed for Surface Mount Application

Mechanical Data

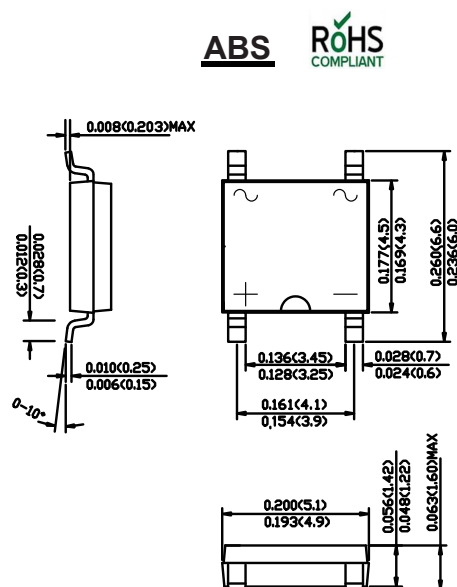
Case : JEDEC ABS Molded plastic body

Terminals : Solder plated, solderable per MIL-STD-750, Method 2026

Polarity : Polarity symbol marking on body

Mounting Position : Any

Weight : 0.0031 ounce, 0.098 grams



Dimensions in inches and (millimeters)

Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	ABS2	ABS4	ABS6	ABS8	ABS10	UNITS
Marking Code		MDD ABS2	MDD ABS4	MDD ABS6	MDD ABS8	MDD ABS10	
Maximum repetitive peak reverse voltage	V_{RRM}	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	200	400	600	800	1000	V
Average Rectified Output Current at $T_c = 125^\circ\text{C}$	$I_{F(AV)}$	1.0					A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	35					A
Maximum instantaneous forward voltage drop per leg at 1A	V_F	1.1					V
Maximum DC reverse current at rated DC blocking voltage $T_A = 25^\circ\text{C}$ $T_A = 100^\circ\text{C}$ $T_A = 125^\circ\text{C}$	I_R	5 50 100					μA
Typical thermal resistance (Note2)	$R_{\theta JA}$ $R_{\theta JC}$	72 20					$^\circ\text{C/W}$
Typical Junction capacitance (Note1)	C_J	13					pF
Operating and storage temperature range	T_J, T_{STG}	-55 to +150					$^\circ\text{C}$

NOTES: 1. Measured at 1MHz and applied reverse voltage of 4 V D.C.

2. Mounted on glass epoxy PC board with $4 \times 1.5" \times 1.5"$ (3.81×3.81 cm) copper pad.

Ratings And Characteristic Curves

Fig.1 Average Rectified Output Current Derating Curve

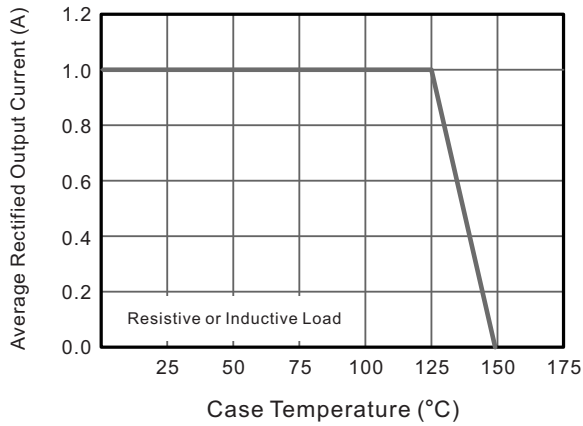


Fig.2 Typical Reverse Characteristics

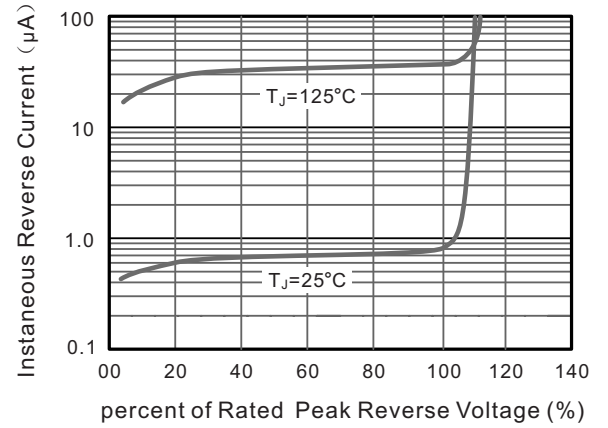


Fig.3 Typical Instantaneous Forward Characteristics

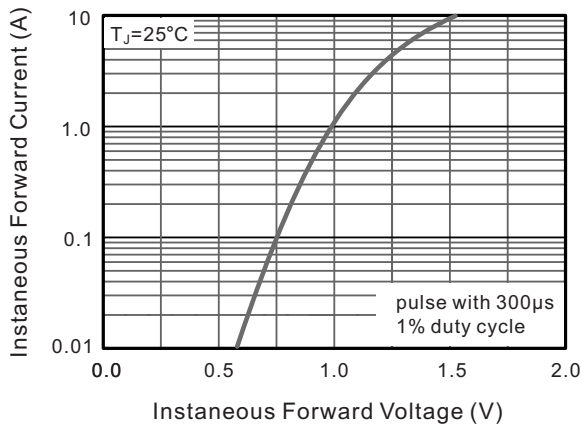


Fig.4 Typical Junction Capacitance

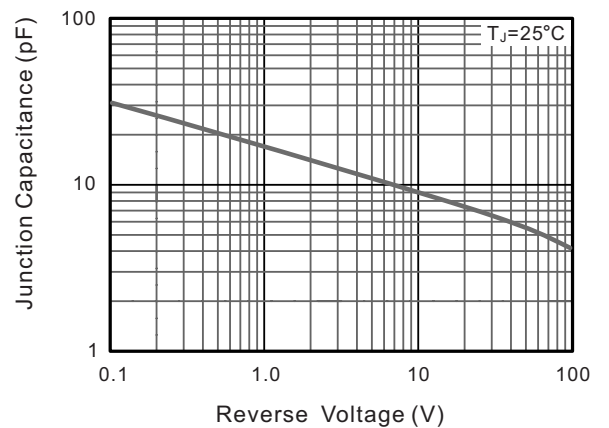
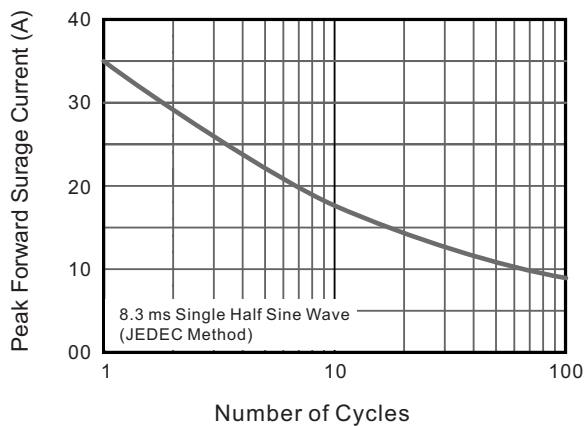
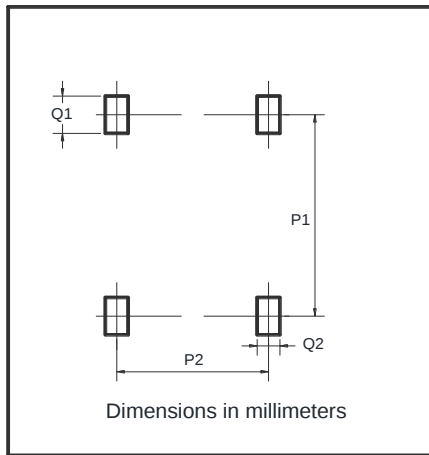


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current



The curve above is for reference only.

Suggested Pad Layout



Dim	Min
P1	5.72
P2	4.00
Q1	1.00
Q2	0.90

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